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As a below named inventor, I hereby declare that:

Prior Provisional Application(s)

My residence, post office and citizenship are as stated below next to my name,

- L affic	ce and citizens	hip are as stated be	1011 110713	•		
My residence, post office I believe I am the original	Ce and one		nome i	s listed	below) or an ori	ginal, first and
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I believe I am the original joint inventor (if plural sought on the invention)	mai, mist are lis	sted below) of the s	subject mate	ced Di	ODE HAVING	A PCB TYPE
ioint inventor (if plural	names are mi	lled SEMICONDL	JCTOR LA	SCII UI	<u> </u>	•
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I hereby state that I including the claims a	os amended by	y any amendment re	ilelled to an			tantobility in
including the claims of	as unions		:- known	to me to	o be material to) bateritaning ""
I hereby state that including the claims at a cknowledge the caccordance with Title	- 27 Code of	Federal Regulations	, Section 1.	00.		Oadion
accordance with Title	e 37, 00d0 or		u. d Cto	tes Cod	de. Section 1196	(a)-(d) or Section
	- mority her	efits under Title 35,	United Sie	dificate	or Section 36	5(a) of any PC1
I acknowledge the accordance with Title I hereby claim foreign accordance with Title I hereby claim foreign accordance with Title I hereby claim foreign accordance with the accordance with Title I hereby claim foreign accordance with the accordance with	ign priority bor	(s) for patent or in	ventor's ce	thar tha	n the United St	ates, listed below
365(b) of any forei	ign application	signated at least on	e country o	a invent	or's certificate h	aving a filing date
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Prior Foreign Appli	ication(s):	Day/Month/Year File	<u>:d</u>	<u>Yes</u>	<u>No</u>	
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2003-65017 K						
2003-030 11					- deienal	application(s) listed
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claim th	ne benefit und	er 35 USC §119(e)	J ,			
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Application Number I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of any PCT international application designating the United States, listed below and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Filing Date

Serial No.

Filing Date

Status: Patented Pending. Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Allan M. Lowe, Reg. No. 19.641; Benjamin J. Hauptman, Reg. No. 29,310; Israel Gopstein, Reg. No. 27,333; Kenneth M. Berner, Reg. No. 37,093; Michael G. Gilman, Reg. No. 19,114; and Randy Noranbrock, Reg. No. 42, 940, all of

with full power of substitution and revocation, to prosecute this application and to transact all business in

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the Patent and Tradento them.	nark Office connected therewith, and all future correspondence should be addressed						
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